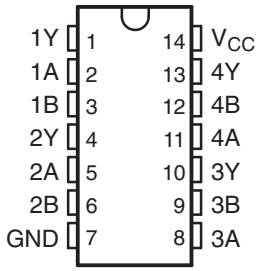
RAD-TOLERANT CLASS V, QUADRUPLE 2-INPUT POSITIVE-NOR GATES

FEATURES

- **AC Types Feature 1.5-V to 5.5-V Operation**
- **Rad-Tolerant: 50 KRad(Si) TID** (1)
  - **TID Dose Rate < 2 mRad/sec**
- **QML-V Qualified, SMD 5962-87612**

(1) Radiation tolerance is a typical value based upon initial device qualification. Radiation Lot Acceptance Testing is available - contact factory for details.

J OR W PACKAGE
(TOP VIEW)



DESCRIPTION

The 'AC02 devices contain four independent 2-input NOR gates that perform the Boolean function $Y = \overline{A} \cdot \overline{B}$ or $Y = \overline{A + B}$ in positive logic.

ORDERING INFORMATION(1)

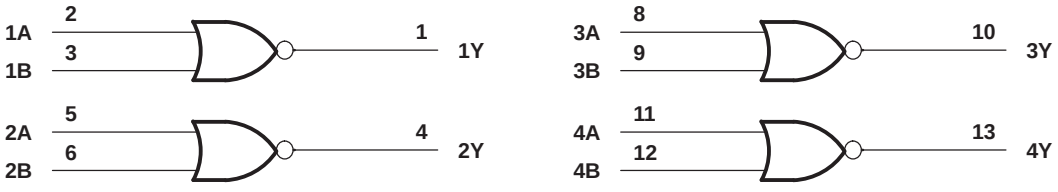
T_A	PACKAGE(2)		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	J - package	tube	5962-8761203VCA	5962-8761203VCA
	W - package		5962-8761203VDA	5962-8761203VDA

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at www.ti.com.
(2) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (EACH GATE)

INPUTS		OUTPUT
A	B	Y
H	X	L
X	H	L
L	L	H

LOGIC DIAGRAM (POSITIVE LOGIC)



ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		–0.5	6	V
I_{IK}	Input clamp current(2)	$V_I < 0$ or $V_I > V_{CC}$		±20	mA
I_{OK}	Output clamp current(2)	$V_O < 0$		±50	mA
I_O	Continuous output current	$V_O = 0$ to V_{CC}		±50	mA
	Continuous current through V_{CC} or GND			±100	mA
T_{stg}	Storage temperature range		–65	150	= C

(1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input and output voltage ratings may be exceeded provided the input and output current ratings are observed.

RECOMMENDED OPERATING CONDITIONS(1)

			T_A = 25°C		–55°C TO 125°C		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		1.5	5.5	1.5	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 1.5 V	1.2		1.2		V
		V_{CC} = 3 V	2.1		2.1		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 1.5 V		0.3		0.3	V
		V_{CC} = 3 V		0.9		0.9	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 4.5 V to 5.5 V		–24		–24	mA
I_{OL}	Low-level output current	V_{CC} = 4.5 V to 5.5 V		24		24	mA
Δt/Δv	Input transition rise or fall rate	V_{CC} = 1.5 V to 3 V		50		50	ns/V
		V_{CC} = 3.6 V to 5.5 V		20		20	

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

ELECTRICAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	T_A = 25°C		–55°C TO 125°C		UNIT
				MIN	MAX	MIN	MAX	
V_{OH}	$V_I = V_{IH}$ or V_{IL}	I_{OH} = –50 µA	1.5 V	1.4		1.4		V
			3 V	2.9		2.9		
			4.5 V	4.4		4.4		
		I_{OH} = –4mA	3 V	2.58		2.4		
		I_{OH} = –24 mA	4.5 V	3.94		3.7		
		I_{OH} = –50 mA(1)	5.5 V			3.85		
V_{OL}	$V_I = V_{IH}$ or V_{IL}	I_{OL} = 50 µA	1.5 V		0.1		0.1	V
			3 V		0.1		0.1	
			4.5 V		0.1		0.1	
		I_{OL} = 12 mA	3 V		0.36		0.5	
		I_{OL} = 24 mA	4.5 V		0.36		0.525	
		I_{OL} = 50 mA(1)	5.5 V				1.65	
I_I	$V_I = V_{CC}$ or GND		5.5 V		±0.1		±1	µA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0		5.5 V		4		80	µA
C_I					10		10	pF

(1) Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, V_{CC} = 1.5 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C TO 125°C		UNIT
			MIN	MAX	
t_{PLH}	A or B	Y		144	ns
t_{PHL}				144	

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C TO 125°C		UNIT
			MIN	MAX	
t_{PLH}	A or B	Y	4	16.1	ns
t_{PHL}			4	16.1	

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

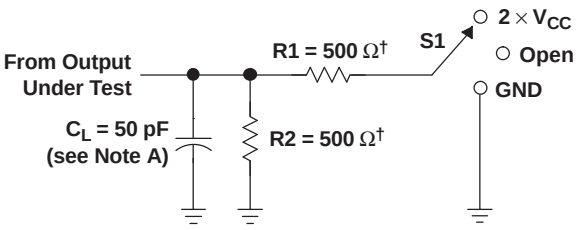
PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C TO 125°C		UNIT
			MIN	MAX	
t_{PLH}	A or B	Y	2.9	11.5	ns
t_{PHL}			2.9	11.5	

OPERATING CHARACTERISTICS

V_{CC} = 5 V, T_A = 25°C

PARAMETER		TYP	UNIT
C_{pd}	Power dissipation capacitance	55	pF

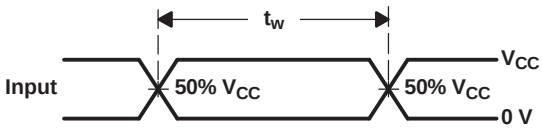
PARAMETER MEASUREMENT INFORMATION



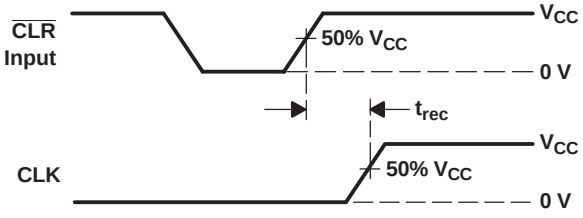
† When V_{CC} = 1.5 V, R1 = R2 = 1 kΩ

LOAD CIRCUIT

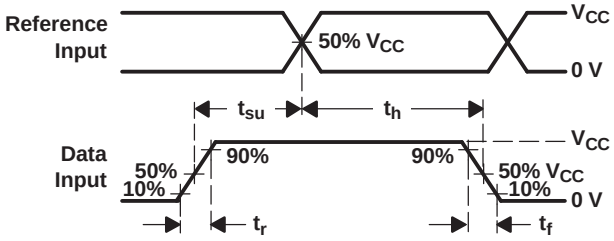
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



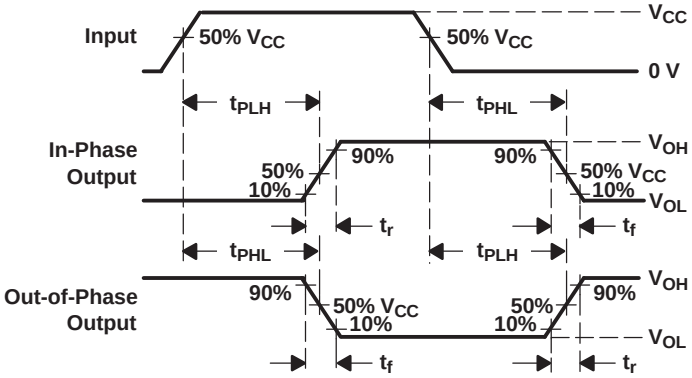
VOLTAGE WAVEFORMS
PULSE DURATION



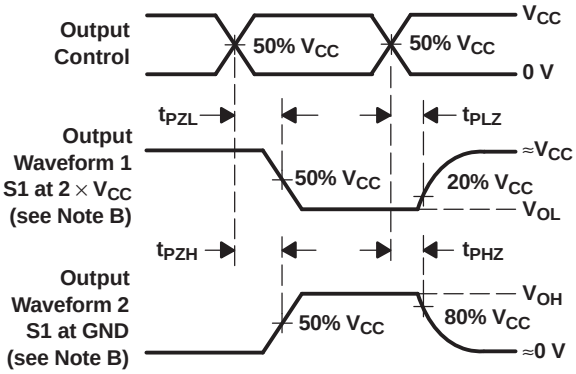
VOLTAGE WAVEFORMS
RECOVERY TIME



VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES



VOLTAGE WAVEFORMS
OUTPUT ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and test-fixture capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns. Phase relationships between waveforms are arbitrary.
D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
E. The outputs are measured one at a time with one input transition per measurement.
F. t_{PLH} and t_{PHL} are the same as t_{pd}.
G. t_{PZL} and t_{PZH} are the same as t_{en}.
H. t_{PLZ} and t_{PHZ} are the same as t_{dis}.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
5962-8761203VCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
5962-8761203VDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

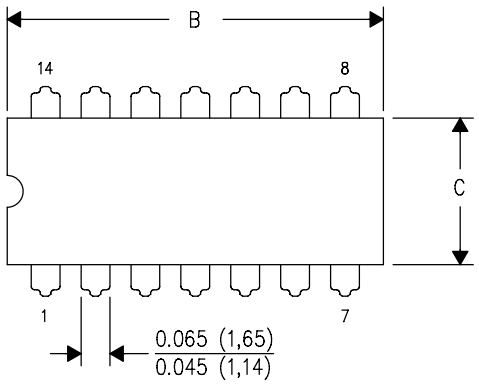
(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

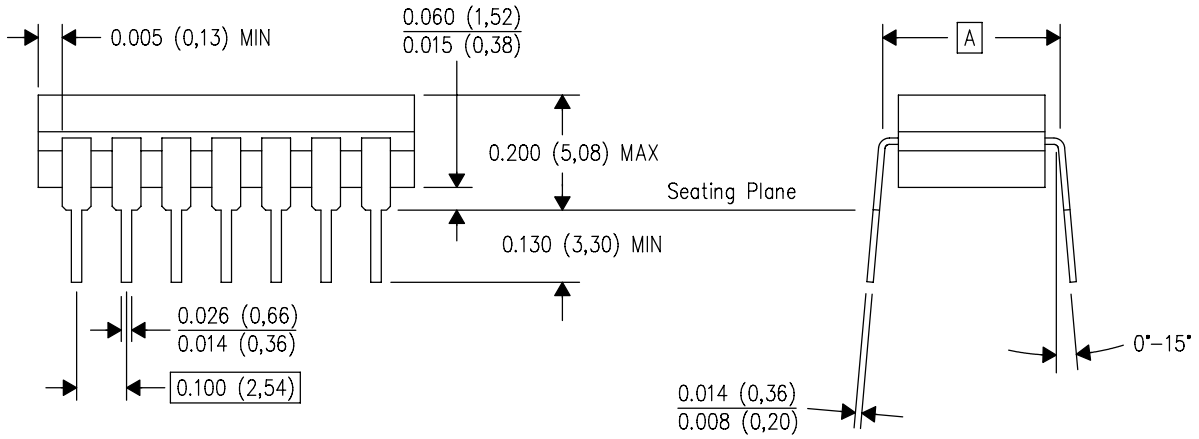
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



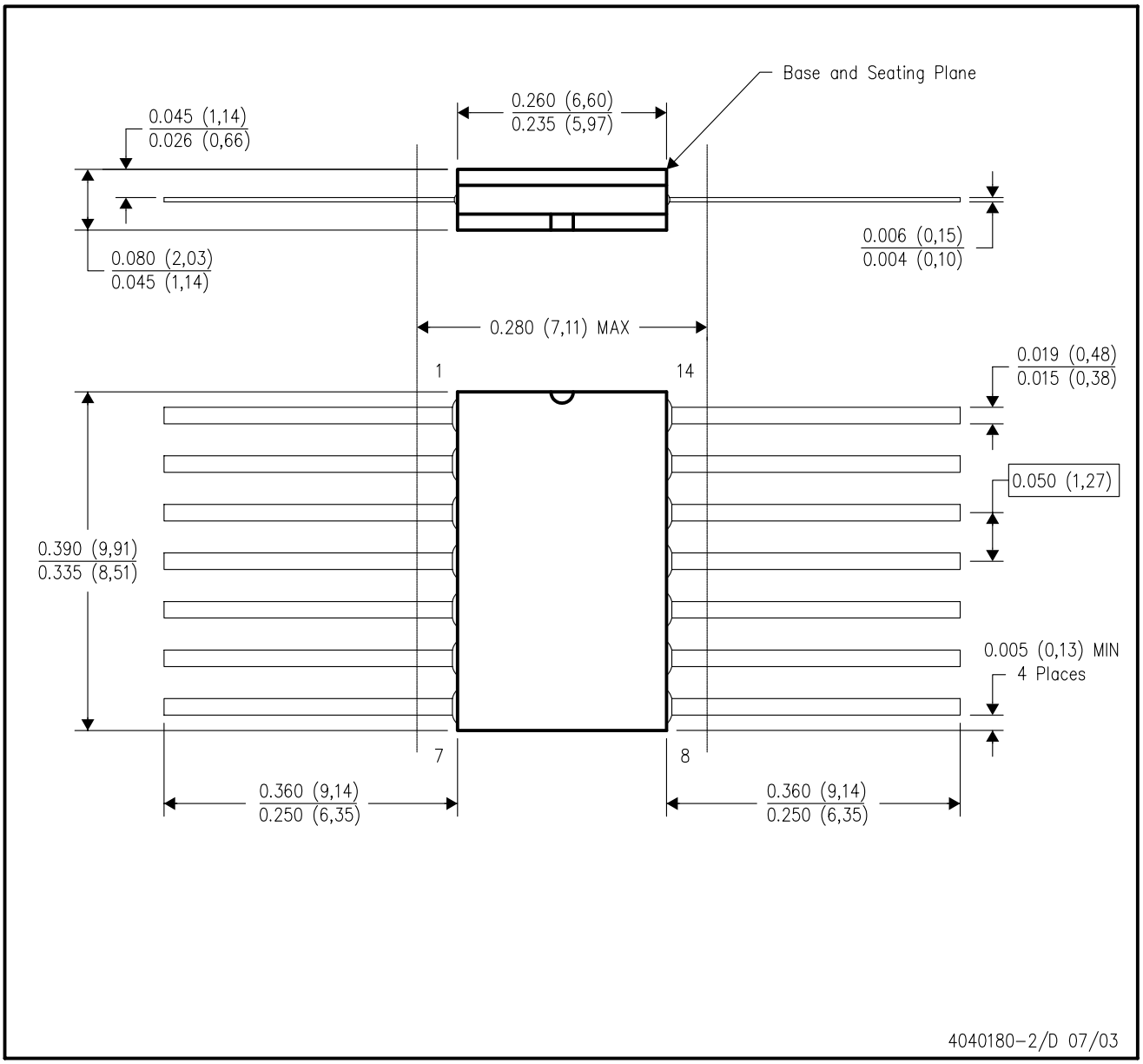
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

W (R–GDFP–F14) CERAMIC DUAL FLATPACK



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F14 and JEDEC MO–092AB

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  Email amall@ameya360.com

  QQ 800077892

  Skype ameyasales1 ameyasales2

- ### Customer Service :

  Email service@ameya360.com

- ### Partnership :

  Tel +86 (21) 64016692-8333

  Email mkt@ameya360.com